

# Global Wire Bonder Equipment Market Status and Outlook 2018-2025

<https://marketpublishers.com/r/G1EA043BDE7EN.html>

Date: July 2018

Pages: 213

Price: US\$ 4,000.00 (Single User License)

ID: G1EA043BDE7EN

## Abstracts

Report Snapshot

Key Content of Chapters (Including and can be customized, report is a semifinished version, and it takes 48-72 hours to upgrade)

Part 1: Terminology Definition, Industry Chain, Industry Dynamics & Regulations and Global Market Overview

Part 2: Upstream (Raw Materials / Components) & Manufacturing (Procurement Methods & Channels and Cost), Major Regional Production Overview and Trade Flow

Part 3: Product Segment Overview and Market Status

Part 4: Application / End-User Segment Overview and Market Status

Part 5: Region Segment Overview and Market Status

Part 6: Product & Application Segment Production & Demand by Region

Part 7: Market Forecast by Product, Application & Region

Part 8: Company information, Products & Services and Business Operation (Sales, Cost, Margin etc.)

Part 9: Market Competition and Environment for New Entrants

Part 10: Conclusion

Market Segment as follows:

Key Companies

ASM Pacific Technology

Kulicke& Soffa

Palomar Technologies

Besi

DIAS Automation

F&K Delvotec Bondtechnik

Hesse

Hybond

SHINKAWA Electric

Toray Engineering

West Bond

#### Market by Type

Ball bonders

Stud-bump bonders

Wedge bonders

#### Market by Application

Integrated Device Manufacturers (IDMs)

Outsourced Semiconductor Assembly and Test (OSAT)

## Contents

### **PART 1 INDUSTRY OVERVIEW (200 USD)**

- 1.1 Wire Bonder Equipment Industry
  - 1.1.1 Market Development
  - 1.1.2 Terminology Definition in the Report
    - 1.1.2.1 Production
    - 1.1.2.2 Demand
    - 1.1.2.3 Sales Revenue
    - 1.1.2.4 Ex-factory Price & Sales Price
    - 1.1.2.5 Cost
    - 1.1.2.6 Gross Margin
- 1.2 Products & Services Scope
- 1.3 Industry Chain
- 1.4 Industry Dynamics & Regulations
- 1.5 Global Market Overview

### **PART 2 UPSTREAM & PRODUCTION (200 USD)**

- 2.1 Raw Materials / Components
- 2.2 Procurement Methods & Channels
- 2.3 Cost Structure & Manufacturing
- 2.4 Industry Capacity
- 2.5 Production Distribution by Geography
  - 2.5.1 Production in Major Regions / Countries
  - 2.5.2 Trade Flow Overview

### **PART 3 PRODUCT SEGMENT (400 USD)**

- 3.1 Introduction by Type
  - 3.1.1 Ball bonders
  - 3.1.2 Stud-bump bonders
  - 3.1.3 Wedge bonders
- 3.2 Market Status

### **PART 4 APPLICATION / END-USER SEGMENT (400 USD)**

- 4.1 Introduction by Application

- 4.1.1 Integrated Device Manufacturers (IDMs)
- 4.1.2 Outsourced Semiconductor Assembly and Test (OSAT)
- 4.2 Market Status

## **PART 5 REGIONAL MARKET (600 USD)**

### 5.1 Market Overview

### 5.2 by Region

#### 5.2.1 North America

- 5.2.1.1 United States Market Size and Growth (2015-2018E)
- 5.2.1.2 Canada Market Size and Growth (2015-2018E)
- 5.2.1.3 Mexico Market Size and Growth (2015-2018E)

#### 5.2.2 Europe

- 5.2.2.1 Germany Market Size and Growth (2015-2018E)
- 5.2.2.2 UK Market Size and Growth (2015-2018E)
- 5.2.2.3 France Market Size and Growth (2015-2018E)
- 5.2.2.4 Italy Market Size and Growth (2015-2018E)
- 5.2.2.5 Spain Market Size and Growth (2015-2018E)
- 5.2.2.6 Netherlands Market Size and Growth (2015-2018E)
- 5.2.2.7 Poland Market Size and Growth (2015-2018E)
- 5.2.2.8 Belgium Market Size and Growth (2015-2018E)
- 5.2.2.9 Sweden Market Size and Growth (2015-2018E)
- 5.2.2.10 Austria Market Size and Growth (2015-2018E)
- 5.2.2.11 Denmark Market Size and Growth (2015-2018E)
- 5.2.2.12 Switzerland Market Size and Growth (2015-2018E)
- 5.2.2.13 Russia Market Size and Growth (2015-2018E)

#### 5.2.3 Asia-Pacific

- 5.2.3.1 China Market Size and Growth (2015-2018E)
- 5.2.3.2 India Market Size and Growth (2015-2018E)
- 5.2.3.3 Japan Market Size and Growth (2015-2018E)
- 5.2.3.4 Korea Market Size and Growth (2015-2018E)
- 5.2.3.5 Australia Market Size and Growth (2015-2018E)
- 5.2.3.6 Indonesia Market Size and Growth (2015-2018E)
- 5.2.3.7 Thailand Market Size and Growth (2015-2018E)
- 5.2.3.8 Malaysia Market Size and Growth (2015-2018E)
- 5.2.3.9 Singapore Market Size and Growth (2015-2018E)
- 5.2.3.10 Philippines Market Size and Growth (2015-2018E)

#### 5.2.4 South America

- 5.2.4.1 Brazil Market Size and Growth (2015-2018E)

- 5.2.4.2 Argentina Market Size and Growth (2015-2018E)
- 5.2.4.3 Columbia Market Size and Growth (2015-2018E)
- 5.2.4.4 Chile Market Size and Growth (2015-2018E)
- 5.2.4.5 Peru Market Size and Growth (2015-2018E)
- 5.2.4.6 Puerto Rico Market Size and Growth (2015-2018E)
- 5.2.4.7 Ecuador Market Size and Growth (2015-2018E)
- 5.2.5 Middle East
  - 5.2.5.1 Saudi Arabia Market Size and Growth (2015-2018E)
  - 5.2.5.2 Iran Market Size and Growth (2015-2018E)
  - 5.2.5.3 UAE Market Size and Growth (2015-2018E)
  - 5.2.5.4 Oman Market Size and Growth (2015-2018E)
  - 5.2.5.5 Kuwait Market Size and Growth (2015-2018E)
  - 5.2.5.6 Iraq Market Size and Growth (2015-2018E)
  - 5.2.5.7 Turkey Market Size and Growth (2015-2018E)
- 5.2.6 Africa
  - 5.2.6.1 South Africa Market Size and Growth (2015-2018E)
  - 5.2.6.2 Egypt Market Size and Growth (2015-2018E)
  - 5.2.6.3 Nigeria Market Size and Growth (2015-2018E)
  - 5.2.6.4 Algeria Market Size and Growth (2015-2018E)
  - 5.2.6.5 Angola Market Size and Growth (2015-2018E)
  - 5.2.6.6 Morocco Market Size and Growth (2015-2018E)
  - 5.2.6.7 Sultan Market Size and Growth (2015-2018E)

## **PART 6 MARKET SUBDIVISION (800 USD)**

- 6.1 Regional Production
  - 6.1.1 Production by Type
    - 6.1.1.1 Ball bonders Production by Region
    - 6.1.1.2 Stud-bump bonders Production by Region
    - 6.1.1.3 Wedge bonders Production by Region
  - 6.1.2 Production by Application
    - 6.1.2.1 Integrated Device Manufacturers (IDMs) Production by Region
    - 6.1.2.2 Outsourced Semiconductor Assembly and Test (OSAT) Production by Region
- 6.2 Regional Demand
  - 6.2.1 Demand by Type
    - 6.2.1.1 Ball bonders Demand by Region
    - 6.2.1.2 Stud-bump bonders Demand by Region
    - 6.2.1.3 Wedge bonders Demand by Region
  - 6.2.2 Demand by Application

6.2.2.1 Integrated Device Manufacturers (IDMs) Demand by Region

6.2.2.2 Outsourced Semiconductor Assembly and Test (OSAT) Demand by Region

## **PART 7 MARKET FORECAST (200 USD)**

7.1 Global Forecast

7.2 Forecast by Type

7.3 Forecast by Application

7.4 Forecast by Region

## **PART 8 KEY COMPANIES LIST (600 USD)**

8.1 ASM Pacific Technology

8.1.2 Company Information

8.1.2 Products & Services

8.1.3 Business Operation

8.2 Kulicke& Soffa

8.2.1 Company Information

8.2.2 Products & Services

8.2.3 Business Operation

8.3 Palomar Technologies

8.3.1 Company Information

8.3.2 Products & Services

8.3.3 Business Operation

8.4 Besi

8.4.1 Company Information

8.4.2 Products & Services

8.4.3 Business Operation

8.5 DIAS Automation

8.5.1 Company Information

8.5.2 Products & Services

8.5.3 Business Operation

8.6 F&K Delvotec Bondtechnik

8.6.1 Company Information

8.6.2 Products & Services

8.6.3 Business Operation

8.7 Hesse

8.7.1 Company Information

8.7.2 Products & Services

- 8.7.3 Business Operation
- 8.8 Hybond
  - 8.8.1 Company Information
  - 8.8.2 Products & Services
  - 8.8.3 Business Operation
- 8.9 SHINKAWA Electric
  - 8.9.1 Company Information
  - 8.9.2 Products & Services
  - 8.9.3 Business Operation
- 8.10 Toray Engineering
  - 8.10.1 Company Information
  - 8.10.2 Products & Services
  - 8.10.3 Business Operation
- 8.11 West Bond

## **PART 9 COMPANY COMPETITION (500 USD)**

- 9.1 Market by Company
- 9.2 Price & Gross Margin
- 9.3 Competitive Environment for New Entrants
  - 9.3.1 Michael Porter's Five Forces Model
  - 9.3.2 SWOT

## **PART 10 RESEARCH CONCLUSION (100 USD)**

## I would like to order

Product name: Global Wire Bonder Equipment Market Status and Outlook 2018-2025

Product link: <https://marketpublishers.com/r/G1EA043BDE7EN.html>

Price: US\$ 4,000.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/G1EA043BDE7EN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:  
Last name:  
Email:  
Company:  
Address:  
City:  
Zip code:  
Country:  
Tel:  
Fax:  
Your message:

**\*\*All fields are required**

Customer signature \_\_\_\_\_

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970